1.6X0.8mm SMD CHIP LED LAMP

AP1608SURC

HYPER RED

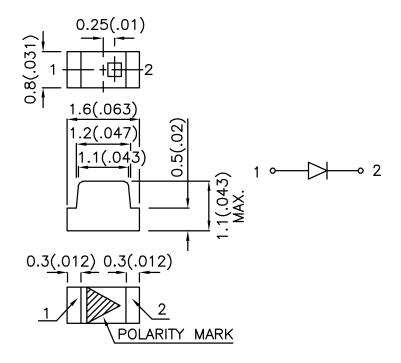
Features

- •1.6mmX0.8mm SMT LED, 1.1mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE: 2000PCS / REEL .
- •Rohs Compliant.

Description

The Hyper Red source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1(0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle
			Min.	Тур.	201/2
AP1608SURC	HYPER RED (InGaAIP)	WATER CLEAR	70	200	120°

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	640		nm	IF=20mA
λD	Dominant Wavelength	Hyper Red	628		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	27		nm	IF=20mA
С	Capacitance	Hyper Red	45		pF	VF=0V;f=1MHz
VF	Forward Voltage	Hyper Red	1.9	2.5	V	IF=20mA
lr	Reverse Current	Hyper Red		10	uA	VR = 5V

Absolute Maximum Ratings at Ta=25°C

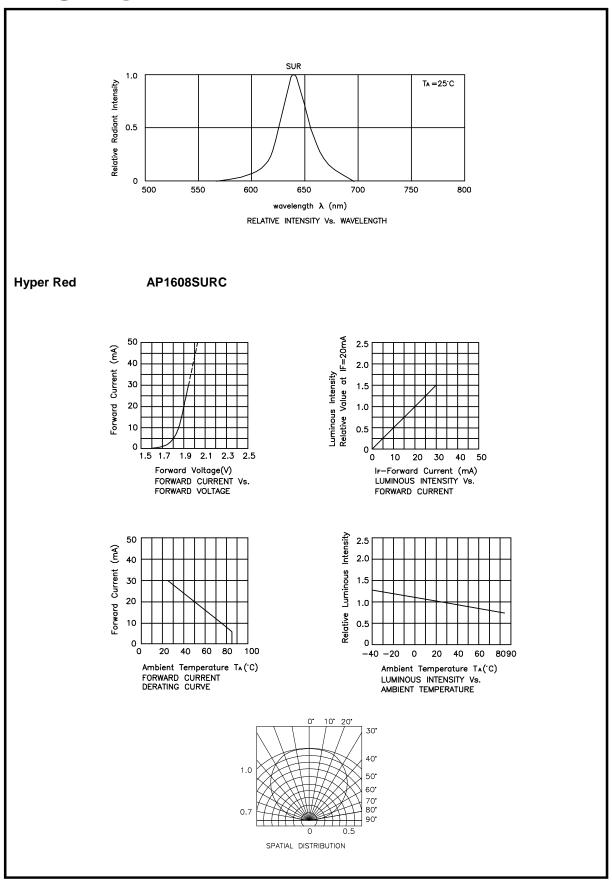
Parameter	Hyper Red	Units
Power dissipation	170	mW
DC Forward Current	30	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

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Note:
1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

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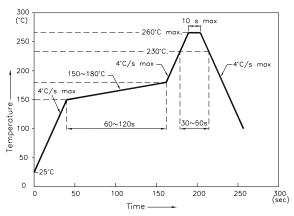
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AP1608SURC

Reflow Soldering Profile For Lead-free SMT Process.



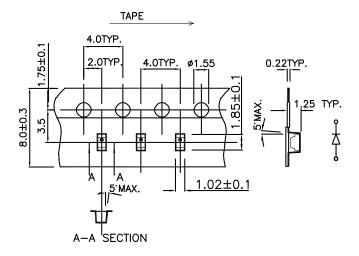
NOTES:

- 1.We recommend the reflow temperature $245^{\circ}\text{C}(+/-5^{\circ}\text{C})$.The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



Remarks:

- If there is sorting requirement (eg. forward voltage, luminous intensity or wavelength), the condition as follows:
- 1. Wavelength: +/-1nm (Test condition is based on the sorting standard).
- 2.Luminous intensity: +/-15% (Test condition is based on the sorting standard).
- 3. Forward voltage: +/-0.1V (Test condition is based on the sorting standard).

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